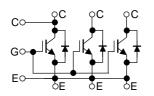
TOSHIBA GTR Module Silicon N-Channel IGBT

MG1200FXF1US51

High Power Switching Applications Motor Control Applications

- High input impedance
- Enhancement mode
- Electrodes are isolated from case.

Equivalent Circuit



Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit
Collector-emitter voltage			V _{CES}	3300	V
Gate-emitter voltage			V _{GES}	±20	V
		RMS	Ι _C	1200 (Note 1)	А
Collector currer	nt	Peak turn off current	I _{CP}	2400 (Note 2)	А
Peak 1 cycle su	urge current	10 ms (half sine)	I _{FSM}	10	kA
Collector power dissipation			P _C	4000	W
Operating junction temperature			Тj	-40~125	°C
Storage temperature range			T _{stg}	-40~125	°C
Isolation voltage			V _{Isol}	6000 (AC 1 min)	V
Screw torque	Terminal: M4/M8 Mounting			2/7	Nm
				4	IN(I)

Caution: MG1200FXF1US51 has no short-circuit capability.

Note 1: 50 Hz (half sine). $T_C = 75^{\circ}C$, switching loss is not contained.

Note 2: $V_{CC} \leq 2200 \text{ V}, V_{CP} \leq 2700 \text{ V}, LS \simeq 160 \text{ nH}, CGE = 0.1 \ \mu\text{F}, RG = 3.3 \ \Omega, \text{ VGE} = \pm 15 \text{V}, Tj \leq 125^{\circ}\text{C}$

Electrical Characteristics ($T_{vj} = 125^{\circ}C$)

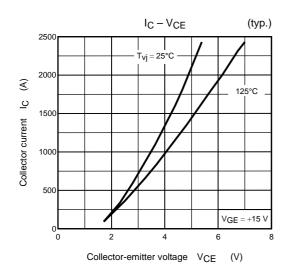
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GES}	$V_{GE}=\pm 20~V,~V_{CE}=0~V$		_	±50	nA
Collector cut-off current		ICES	$V_{CE} = 3300 \text{ V}, \text{ V}_{GE} = 0 \text{ V}$		75	100	mA
Gate-emitter cut-off voltage		V _{GE (off)}	$V_{CE} = 5 \text{ V}, I_{C} = 1.2 \text{ A}$	_	4.4	_	V
Collector-emitter saturation voltage		V _{CE (sat)}	$I_{C} = 1200 \text{ A}, V_{GE} = 15 \text{ V}$	_	4.6	5.3	V
Input capacitance		C _{ies}	$V_{CE} = 10 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$	_	230	_	nF
Switching time	Rise time	tr	$\label{eq:VCC} \begin{array}{l} V_{CC} = 1800 \; V, \; I_{C} = 1200 \; A, \\ V_{GG} = \pm 15 \; V, \; C_{GE} = 0.1 \; \muF, \\ RG \; (on)/(off) = 3.9/3.3 \; \Omega \\ (dic/dt \; (on) \simeq 4900 \; A/\mu s) \\ (Inductive \; load, \; L_{s} \simeq 160 \; nH) \end{array}$	_	0.3		μS
	Turn-on time	t _{on}			2.1		μS
	Fall time	t _f			1.8		μS
	Turn-off time	t _{off}			4.0	_	μs
Forward voltage of diode		VF	I _F = 1200 A, V _{GE} = 0 V		3.5	4.0	V
Reverse recovery charge		Q _{rr}	I _F = 1200 A, V _{GG} = −15 V, di _F /dt ≃ 4900 A/μs,		1000	_	μC
Peak reverse recovery current		I _{rr}	$V_{CC} = 1800 \text{ V}$	_	1500		А
Switching dissipation	turn-on loss	E _{on}	$\begin{split} V_{CC} &= 1800 \text{ V, } I_C = 1200 \text{ A,} \\ V_{GG} &= \pm 15 \text{ V, } C_{GE} = 0.1 \mu\text{F,} \\ \text{RG (on)/(off)} &= 3.9/3.3 \Omega \\ (\text{dic/dt (on)} &\simeq 4900 \text{ A/}\mu\text{s}) \\ (\text{Inductive load, } L_\text{s} &\simeq 160 \text{ nH}) \end{split}$	_	2.2	2.8	J
	turn-off loss	E _{off}			2.0	3.0	J
	Diode reverse recovery loss	E _{dsw}	$I_{F} = 1200 \text{ A}, V_{GG} = -15 \text{ V},$ $di_{F}/dt \simeq 4900 \text{ A}/\mu\text{s},$ $V_{CC} = 1800 \text{ V}$		1.0	1.5	J

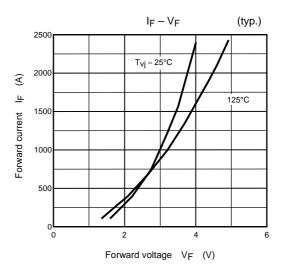
Thermal Resistance (Tc = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
	Pu ()	Transistor (IGBT) stage	_	_	8.0		
Thermal Resistance	R _{th (j-c)}	Diode stage			16.0	°C/kW	
	R _{th (c-f)}	Per module (Note 3)	_	6.0	_		

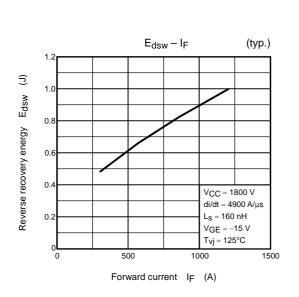
Note 3: Toshiba silicone's YG6260 heat radiation grease is recommended for use with semiconductor devices. Apply a thin, even (100-to-200-μm) coating of grease.

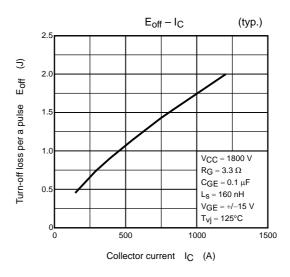
TOSHIBA

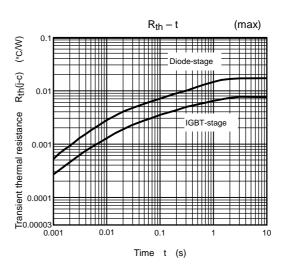




 $E_{on} - I_C$ (typ.) 2.5 5 2.0 Eon Turn-on loss per a pulse 1.5 1.0 V_{CC} = 1800 V $R_G=3.9\;\Omega$ $C_{GE}=0.1\ \mu F$ 0.5 L_S = 160 nH V_{GE} = +/-15 V T_{Vj} = 125°C 0**L** 0 500 1000 1500 Collector current IC (A)

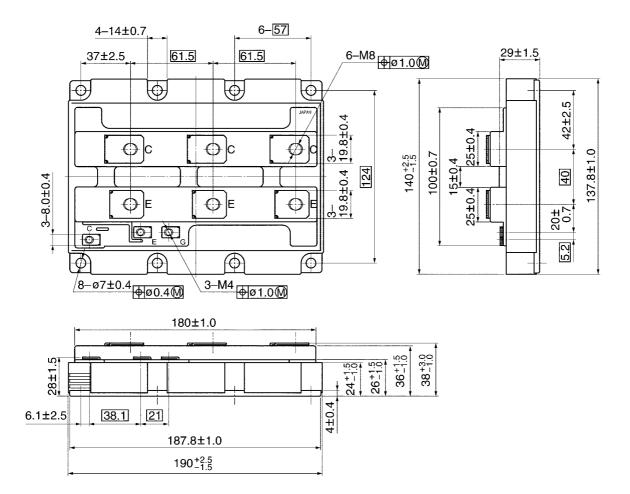






Package Dimensions: 2-193A1A

Unit: mm



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Handbook" etc.,

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